

RoHS COMPLIANCE STATEMENT

1. SCOPE

This statement clarifies all JPR Electronics products compliance with the European Union's directive 2015/863/EU, Restrictions of Hazardous Substances ("RoHS" directive) and similar regulations that may be adopted by other countries.

RoHS directive became valid on July 1 2006 in the member states of European Union. It states that all new electrical and electronic equipment supplied within the member states must not contain certain hazardous materials.

2. RESTRICTED (RoHS) MATERIALS

Quantity limit 0.1% of weight (1000 ppm) of any homogeneous material:

1. Lead (Pb).
2. Mercury (Hg).
3. Hexavalent Chromium (Cr VI).
4. Flame retardant Polybrominated Biphenyls (PBB)
5. Flame retardant Polybrominated Diphenyl Ethers (PBDE).
6. Bis(2-ethylhexyl) phthalate (DEHP)
7. Benzyl butyl phthalate (BBP)
8. Dibutyl phthalate (DBP)
9. Diisobutyl phthalate (DIBP)

Quantity limit 0.01% of weight (100 ppm) of any homogeneous material:

10. Cadmium (Cd).

'Homogeneous material' means a material that cannot be mechanically disjointed into different materials by, for example unscrewing, cutting, crushing, grinding and abrasive processes. Homogeneous is further defined as "of uniform composition throughout".

3. EXEMPTIONS

Following cases are exempted from the requirements:

1. Copper alloy containing up to 4% lead by weight. (Annex III, 6(c))
2. Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signalling, transmission, and network management for tele-communications. (Annex III, 7(b))
3. Cadmium and lead in filter glasses and glasses used for reflectance standards. (Annex III, 13(b))
4. Lead as an alloying element in steel containing up to 0,35 % lead by weight, aluminium containing up to 0,4 % lead by weight and as a copper alloy containing up to 4 % lead by weight. (Annex III, 6(b))
5. Lead in high melting temperature type solders (i.e. tin-lead solder alloys containing more than 85 % lead), (Annex III, 7(a))
 - lead in solders for servers, storage and storage array systems (exemption granted until 2010),
 - lead in solders for network infrastructure equipment for switching, signalling, transmission as well as network management for telecommunication,
 - lead in electronic ceramic parts (e.g. piezoelectronic devices).
6. Cadmium plating except for applications banned under Directive 91/338/EEC ⁽¹⁾ amending Directive 76/769/EEC ⁽²⁾ relating to restrictions on the marketing and use of certain dangerous substances and preparations
 - lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signalling, transmission as well as network management for telecommunications (with a view to setting a specific time limit for this exemption), and
 - light bulbs,

as a matter of priority in order to establish as soon as possible whether these items are to be amended accordingly.

4. RoHS COMPLIANCE STATEMENT

I certify to the best of my knowledge, based on available information conducted to me, as follows:

All JPR Electronics products, with the listed allowed exceptions, do not contain any homogeneous material that:

- a) contains lead (Pb) in excess of 0.1% by weight (1000 ppm)
- b) contains mercury (Hg) in excess of 0.1% by weight (1000 ppm)
- c) contains hexavalent chromium (Cr VI) in excess of 0.1% by weight (1000 ppm)
- d) contains polybrominated biphenyls (PBB) or polybrominated dimethyl ethers (PBDE) in excess of 0.1% by weight (1000 ppm)
- e) contains cadmium (Cd) in excess of 0.01% by weight (100 ppm)
- f) contains Bis(2-ethylhexyl) phthalate (DEHP) in excess of 0.1% by weight (1000 ppm)
- g) contains Butyl benzyl phthalate (BBP) in excess of 0.1% by weight (1000 ppm)
- h) contains Dibutyl phthalate (DBP) (0.1 %) in excess of 0.1% by weight (1000 ppm)
- i) contains Diisobutyl phthalate (DIBP) in excess of 0.1% by weight (1000 ppm)

Signature:

P. Raynor

Name (printed) Paul Raynor
Title: Director
Date: 29/03/2019